

Characteristics ($T_j = 25^\circ\text{C}$)Kennwerte ($T_j = 25^\circ\text{C}$)

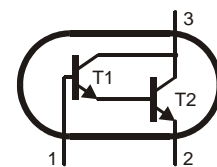
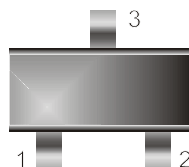
		Min.	Typ.	Max.
Base saturation voltage – Basis-Sättigungsspannung ¹⁾ $I_C = 100\text{ mA}, I_B = 0.1\text{ mA}$				1.5 V
				V_{BEsat}
DC current gain – Kollektor-Basis-Stromverhältnis ¹⁾ $V_{CE} = 5\text{ V}, I_C = 1\text{ mA}$		BCV27 4000	–	–
		BCV47 2000	–	–
$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}$		BCV27 10000	–	–
		BCV47 4000	–	–
$V_{CE} = 5\text{ V}, I_C = 100\text{ mA}$		BCV27 20000	–	–
		BCV47 10000	–	–
Base-Emitter voltage – Basis-Emitter-Spannung ¹⁾ $V_{CE} = 5\text{ V}, I_C = 10\text{ mA}$				1.4 V
				$-V_{BEon}$
Gain-Bandwidth Product – Transitfrequenz $V_{CE} = 5\text{ V}, I_C = 10\text{ mA}, f = 100\text{ MHz}$			220 MHz	–
				f_T
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft		R_{thA}		420 K/W ²⁾
Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren				BCV26, BCV46

Marking – Stempelung

BCV27 = FF

BCV47 = FG

Pinning – Anschlußbelegung



¹⁾ Tested with pulses $t_p = 300\ \mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300\ \mu\text{s}$, Schaltverhältnis $\leq 2\%$

²⁾ Mounted on P.C. board with 3 mm^2 copper pad at each terminal
Montage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluß